

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KUN WU HUANG	06/23/2017
WINSTON LEI ZHANG	06/23/2017
CHAO CHEN	06/23/2017
JINGJING LIU	06/23/2017
DUKE HONGTAO DAI	06/23/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	EMC IP HOLDING COMPANY LLC
<b>Street Address:</b>	176 SOUTH STREET
<b>City:</b>	HOPKINTON
<b>State/Country:</b>	MASSACHUSETTS
<b>Postal Code:</b>	01748
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17186551
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	00552/EMC-16-0342.03
<b>NAME OF SUBMITTER:</b>	ROBYN L. LECESSÉ
<b>SIGNATURE:</b>	/Robyn L. Lecesse/
<b>DATE SIGNED:</b>	02/26/2021
<b>Total Attachments: 7</b>	
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ASSIGNMENT

**WHEREAS**, we, Kun Wu Huang, Winston Lei Zhang, Chao Chen, Jingjing Liu and Duke Hongtao Dai, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled *METHOD AND DEVICE FOR PROCESSING A MULTI-LANGUAGE TEXT* (Application), the specification of which:

- ☐ is being executed on even date herewith and is about to be filed in the United States Patent Office;
- ☒ was filed on June 21, 2017 as U.S. Application No. 15/628,962;
- ☐ was patented under U.S. Patent No. \_\_\_\_\_ on \_\_\_\_\_.

**WHEREAS**, EMC IP HOLDING COMPANY LLC (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the State of Delaware and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

**AND**, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

**AND**, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

**AND**, we hereby authorize our attorneys, EMC IP HOLDING COMPANY LLC, to insert here in parenthesis (15/628,962 filed June 21, 2017) the application number and filing date of said Application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

**IN TESTIMONY WHEREOF**, we have hereunto set our hands and affixed our seals as set forth below:

Date: 2017.6.23 Kunwu Huang  
Inventor's Signature

Print full name of inventor Kun Wu Huang  
Residence EMC Corporation, 2F., Building #2, KIC Plaza,  
No. 252 Songhu Road  
200433 Shanghai, CN  
Citizenship CN  
Mailing Address Same as above

I, Jack Wang (name of first witness), whose residential address is  
2F, #2, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Kun Wu Huang (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

Jack Wang (Signature of first witness)  
Signed at 2F, #2, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23th, 20 17 (date of signature).

I, Tim Ma (name of second witness), whose residential address is  
2F, #2, 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Kun Wu Huang (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

Tim Ma (Signature of second witness)  
Signed at 2F, #2, 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23th, 20 17 (date of signature).

Date: 06/23/2017 Lei Zhang  
Inventor's Signature

Print full name of inventor Winston Lei Zhang  
Residence EMC Corporation, 2F, Building #2, KIC Plaza,  
No. 252 Songhu Road  
Shanghai, CN  
Citizenship CN  
Mailing Address Same as above

I, Jack Wang (name of first witness), whose residential address is  
2F, #2, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Winston Lei Zhang (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

Jack Wang (Signature of first witness)  
Signed at 2F, #2, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, Jun. 23rd, 20 17 (date of signature).

I, Tony Ma (name of second witness), whose residential address is  
2F, 2<sup>nd</sup>, 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Winston Lei Zhang (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

Tony Ma (Signature of second witness)  
Signed at 2F, 2<sup>nd</sup>, 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23rd, 20 17 (date of signature).

Date: Jun 23. 2017

陈超

Inventor's Signature

Print full name of inventor

Chao Chen

Residence

EMC China R&D Center, 2F., Building #2,  
KIC Plaza, No. 252 Songhu Road  
200433 Shanghai, CN

Citizenship

CN

Mailing Address

Same as above

I, Jack Wang (name of first witness), whose residential address is  
2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Chao Chen (name of person signing the assignment), who is  
personally known to me, execute the above assignment.

王杰

(Signature of first witness)

Signed at 2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, Jun. 23th, 20 17 (date of signature).

I, Zong Ma (name of second witness), whose residential address is  
2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Chao Chen (name of person signing the assignment), who is  
personally known to me, execute the above assignment.

马宗

(Signature of second witness)

Signed at 2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23th, 20 17 (date of signature).

Date: 06/23/2017

Li Jingjing Liu  
Inventor's Signature

Print full name of inventor

Jingjing Liu

Residence

EMC Corporation, 2F., Building #2, KIC Plaza,  
No. 252 Songhu Road  
200433 Shanghai, CN

Citizenship

CN

Mailing Address

Same as above

I, Jack Wang (name of first witness), whose residential address is  
2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Jingjing Liu (name of person signing the assignment), who is  
personally known to me, execute the above assignment.

Jack Wang (Signature of first witness)  
Signed at 2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23rd, 2017 (date of signature).

I, Tong Ma (name of second witness), whose residential address is  
2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Jingjing Liu (name of person signing the assignment), who is  
personally known to me, execute the above assignment.

Tong Ma (Signature of second witness)  
Signed at 2F, 2#, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23rd, 2017 (date of signature).



Date: 06/23/2017

代洪涛 Hongtao Dai  
Inventor's Signature

Print full name of inventor

Duke Hongtao Dai

Residence

EMC Corporation, 2F, Building #2, KIC Plaza,  
No. 252 Songhu Road  
200433 Shanghai, CN

Citizenship

CN

Mailing Address

Same as above

I, Jake Wolf (name of first witness), whose residential address is  
2F, 2nd, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Duke Hongtao Dai (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

Jake Wolf (Signature of first witness)  
Signed at 2F, 2nd, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23rd, 20 17 (date of signature).

I, Tong Ma (name of second witness), whose residential address is  
2F, 2nd, No. 252, Songhu Rd, Yangpu, Shanghai  
was personally present and did see Duke Hongtao Dai (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

Tong Ma (signature of second witness)  
Signed at 2F, 2nd, No. 252, Songhu Rd, Yangpu, Shanghai (location of witness signature)  
on this day, June 23rd, 20 17 (date of signature).